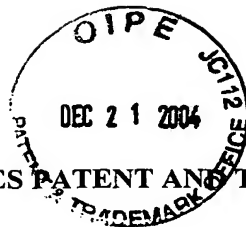


Docket No. 220040US2PCT



COPY

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Claude JAUSSAUD, et al.

SERIAL NO: New US PCT application based on PCT/FR00/02468

GAU:

FILED: Herewith

EXAMINER:

FOR: CREATION OF AN ELECTRICALLY CONDUCTING BONDING BETWEEN TWO SEMI-CONDUCTOR ELEMENTS

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- ☒ The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- ☐ Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- ☐ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- ☒ Please charge any additional fees for the papers being filed herewith and for which no check is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Marvin J. Spivak

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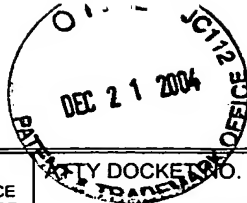
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(OSMMN 10/01)



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		PATENT DOCKET NO. 220040US2PCT		SERIAL NO. New US PCT application based on PCT/FR00/02468	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Claude JAUSSAUD, et al.			
				FILING DATE Herewith		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA	5 441 911	08/15/95	Satwinder MALHI			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	AO	0 587 996	03/23/94	EP			No
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	C.L. SHIEH et al.: "A 1.3 μ m InGaAsP ridge waveguide laser on GaAs and silicon substrates by thin-film transfer" THIRD INTERNATIONAL CONFERENCE ON INDIUM PHOSPHIDE AND RELATED MATERIALS, CARDIFF, UK, pages 272-275 04/08/91-04/11/91					
	AX	Y. LU et al.: "Eutectic bonding for inducing in-plane strain in GaAs and GaAs-AlGaAs MQW thin films" ADVANCED METALLIZATION FOR DEVICES AND CIRCUITS-SCIENCE, TECHNOLOGY, AND MANUFACTURABILITY SYMPOSIUM, pages 607-612 04/04/94-04/08/94					
	AY	R.F. WOLFFENBUTTEL: "Low-temperature intermediate Au-Si wafer bonding; eutectic or silicide bond" SENSORS AND ACTUATORS A (PHYSICAL), vol. A62, no. 1-3, pages 680-686 07/97					
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner					Date Considered		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							